



SEMICON Japan

## **ERS shows new thermal system for evolving test market**

MUNICH, November 19, 2013 - ERS electronic GmbH, the innovation leader for thermal wafer chucks in semiconductor test, will display the newest addition to its AC3 Thermal Chuck System product family, the AC3 AUTOLAB, at the SEMICON Japan next month.

“The line between front end test and back end test is already blurred”, said ERS general manager Klemens Reitingner. “Now we see testing procedures beyond sort and parametric test showing up on production wafer test floors and hear laboratories ask for more automation.” The AUTOLAB configuration was designed with this trend in mind.

Mr. Reitingner went on to say “There is an AUTOLAB configuration available for virtually any wafer prober, application or budget. We are combining our established AC3 thermal controller with new software and have developed a new, optimized chuck structure. We are reducing our lead times for this new configuration by up to 40% and offering exciting new features and test performance.” Among the new software features are Auto-Hold Mode and PC-based options such as Remote Operation and Statistical Data Analysis tool kits. Temperature ranges from -60°C to +400°C are available as are configurations for High Voltage, High Current, High Frequency, Heat Dissipation and Magnetically Neutral applications. Special plating and vacuum patterns are available for the chuck top surface to match the specific configurations.

The AUTOLAB is constructed with optimized capacitance uniformity and has the same short thermal path of the standard AC3 to keep thermal cycling times short and integration into automatic wafer probers simple while still addressing the low noise requirements of laboratory wafer test applications.

By April 2014, ERS AC3 systems (standard and AUTOLAB) will be available with ERS AIRSOAK, an optional, independent air management system that gives users the ability to direct controlled hot or cold temperatures to peripheral locations and devices in the test area as well as to the chuck itself.

SEMICON Japan will take place from December 4-6, 2013 at the Makuhari Messe near Tokyo. The ERS booth can be found in Hall 2, Booth # 2A-609.

For more information visit [www.ers-gmbh.com](http://www.ers-gmbh.com)

### **About ERS electronic GmbH:**

ERS electronic GmbH, located near Munich, is in its 40th year of supplying the most innovative thermal test solutions to the semiconductor industry. The most famous products are its fast-ramping and precise low-noise thermal chuck systems (-65°C to +500°C) for analytical, parametric and wafer sort probing up to 300mm. ERS also designs and builds stand-alone thermal-forcing systems and custom production tools for special applications. ERS invented the AirCool®, AirCool® plus and PowerSense® thermal chuck systems that have been fully integrated into all major manual, semi- and fully automatic wafer probers.

**Press contact:** Timothy K. Goebel - Brand+Image - +49 8143 99 268 34 - [www.brandandimage.de](http://www.brandandimage.de)